

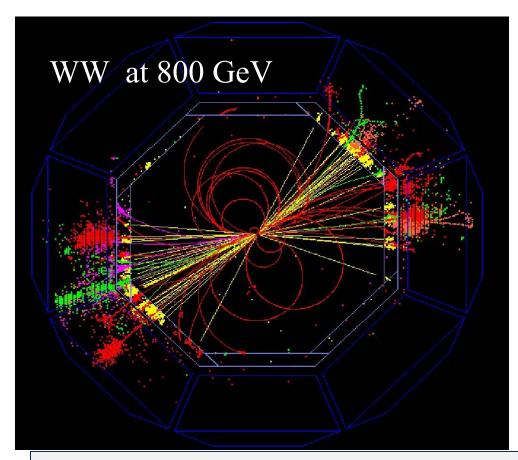
# Silicon tungsten ultraganular electromagnetic calorimeter

Jean-Claude Brient

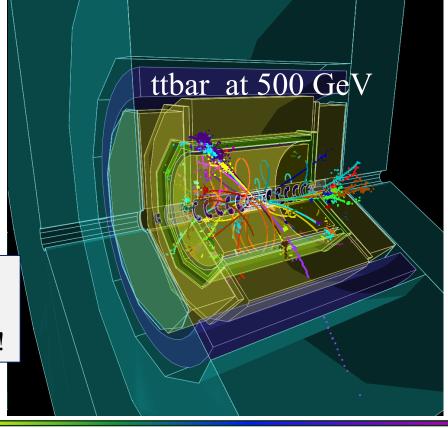
Laboratoire Leprince-Ringuet
CNRS- IP Paris



## We are talking of Imaging calorimetry

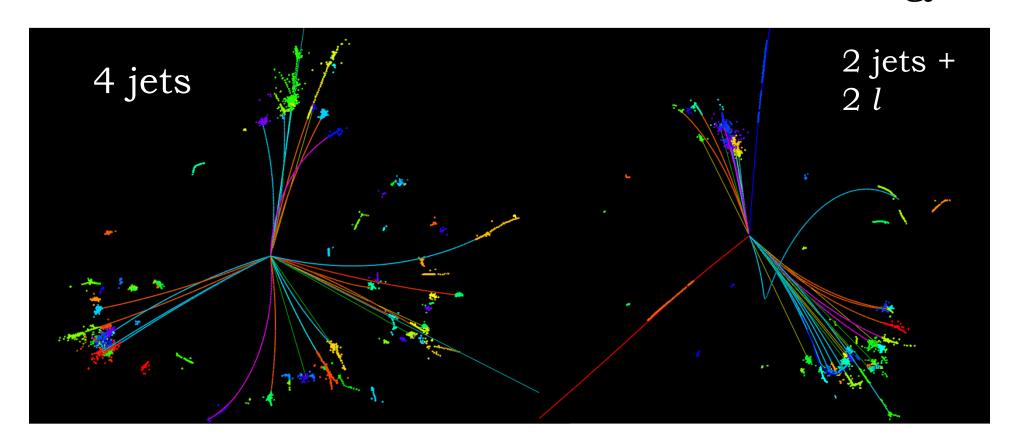


From G4 simulation, the expected performances are a convolution of the detector design and recons. software !!!





## ZH final state at 250 GeV centre of mass energy



Thanks to Manqi Ruan, using ARBOR for CEPC



## Silicon tungsten ECAL

#### **PRO**

#### Why tungsten

- Smaller Moliere radius
- Very good ratio thickness/radiation length

#### Why Silicon

- Response uniform
- Stable, no aging
- S/N at the mip larger than 12
- All in industry
- Performances
- Possible time measrt for individual particle

#### Why carbon fiber

- No dead zone
- Auto hanging system
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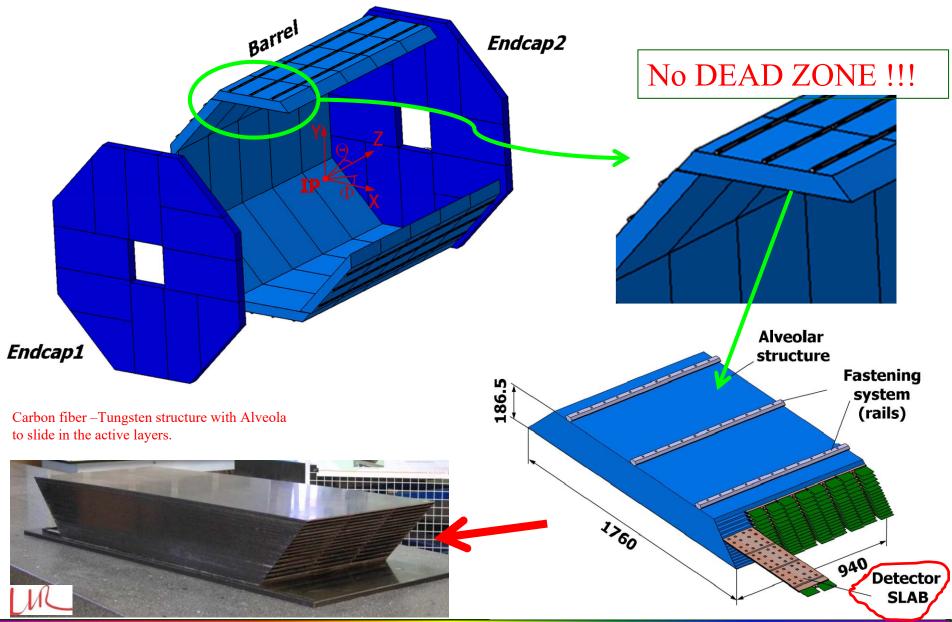
The gain in thickness for silicon Partially compensate the difference of cost on the rest of the detector

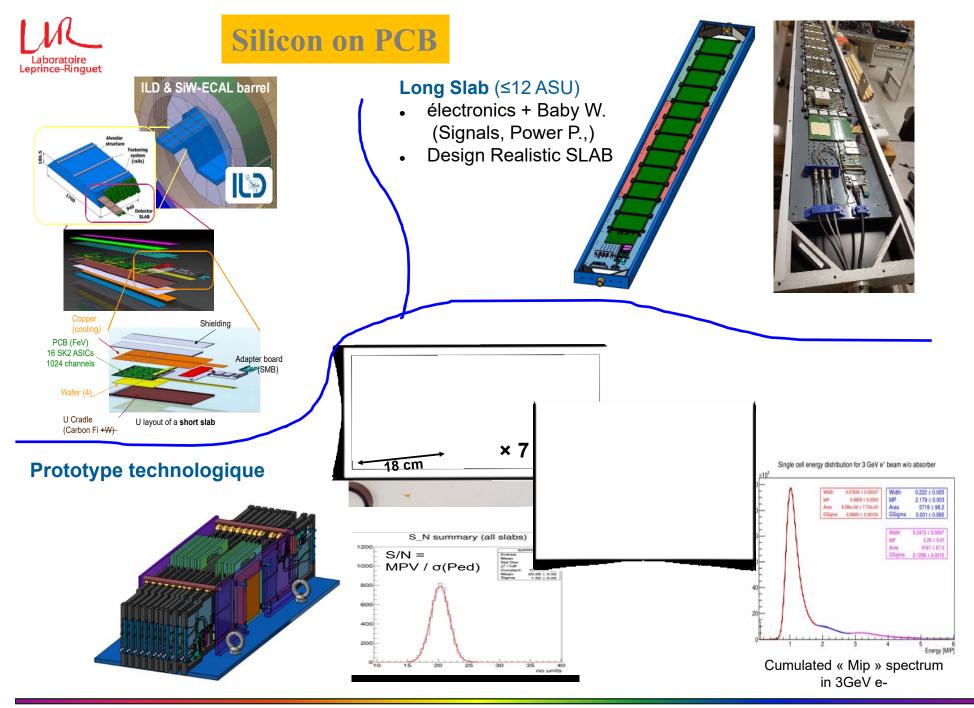
$$30 \times (0.3 - 0.075) = 6.7 \text{ cm}$$



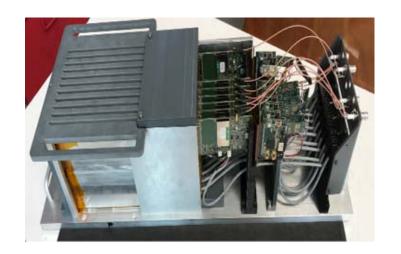
### Carbon fiber structure





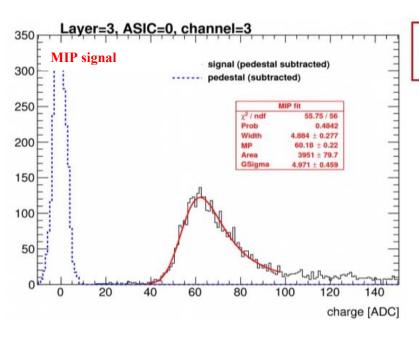


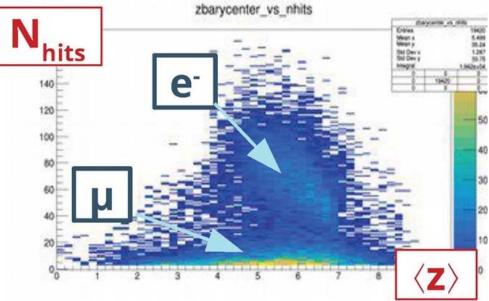




Beam test 2017-2018

Silicon diode 5x5 mm<sup>2</sup> 7 layers







## Long slab lab test

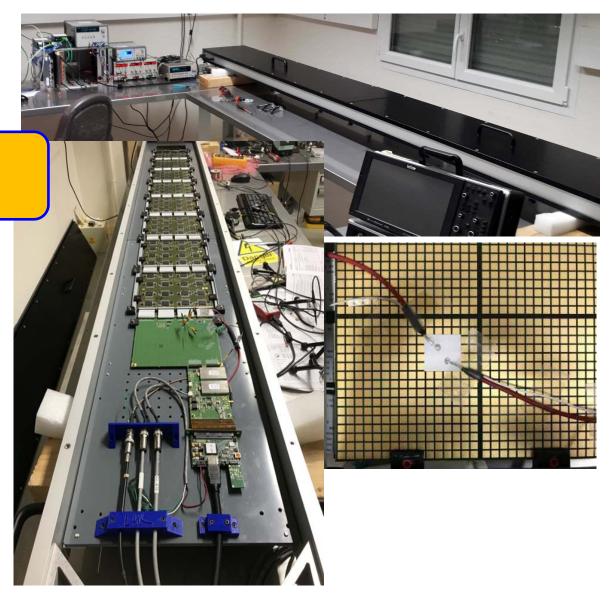
#### Scale to support electronics

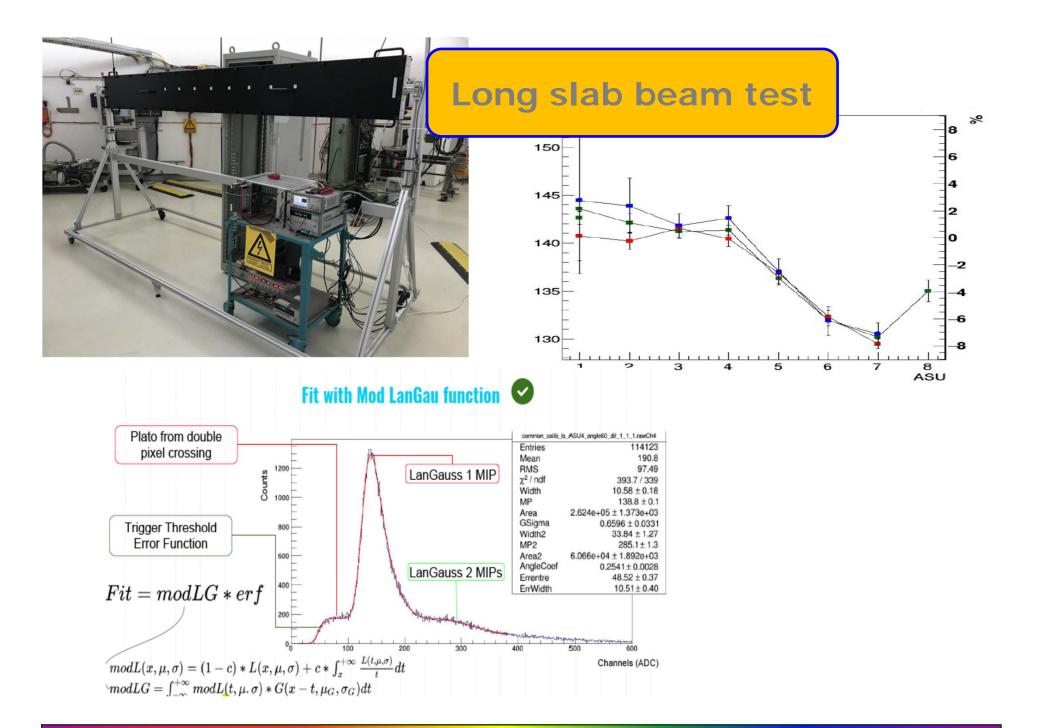
- Support of interface boards + 12 ASUs (DBD)
- 2+6+4 ASUs = ~3.2 m Max length for Endcaps
- Total access to upper and lower parts
  - 320µm Baby wafers (20×20 mm², 4×4 pixels)

#### Mechanical characteristics

- Movable: table and to beam test
- Rotatably along long axis (for beam test)
   Rigidity : ≤ ~1 mm for 3m
- No electrical contacts scale / cards

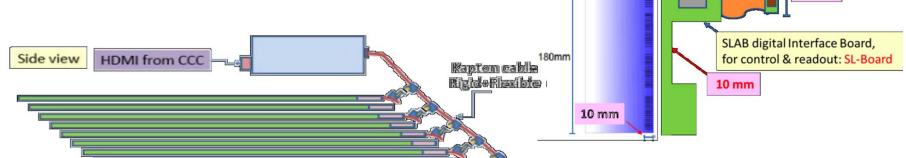
#### Shielding vs Light and CEM







## DAQ system in reduced space

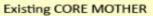


SL-Board

Last E-CAL ASU

42 mm

70 mm



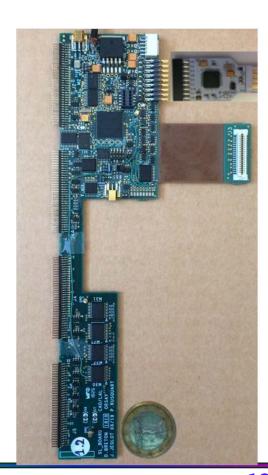


#### ILD spacing constraints:

- between ECAL and HCAL: 67 mm
- Height ≤ 6 to 12 mm depending on the location
- L-shape because of the cooling system
- Control & Readout electronics at the extremity of the Slab
- Signal Integrity over a Slab: up to 8–12 interconnected ASUs (200 ASICs, ~10,000 ch)
- Very low Power consumption(~ 150 mA/ Slab): needs to run in power pulsing mode

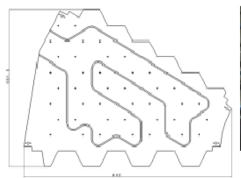
#### New HW: SL-Board

- Regulated PS: HV and LV + monitoring (ADC)
- Controls ASICs & perform RO: ALTERA MAX10 (CPLD+FPGA)
- Connection to CoreModule by single Kapton 40-pin cable
- Low power (<1W)</p>

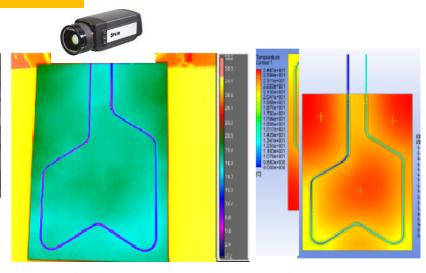




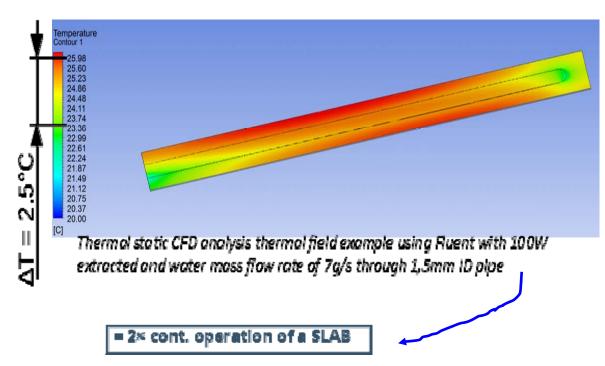
## **COOLING for continuous readout**







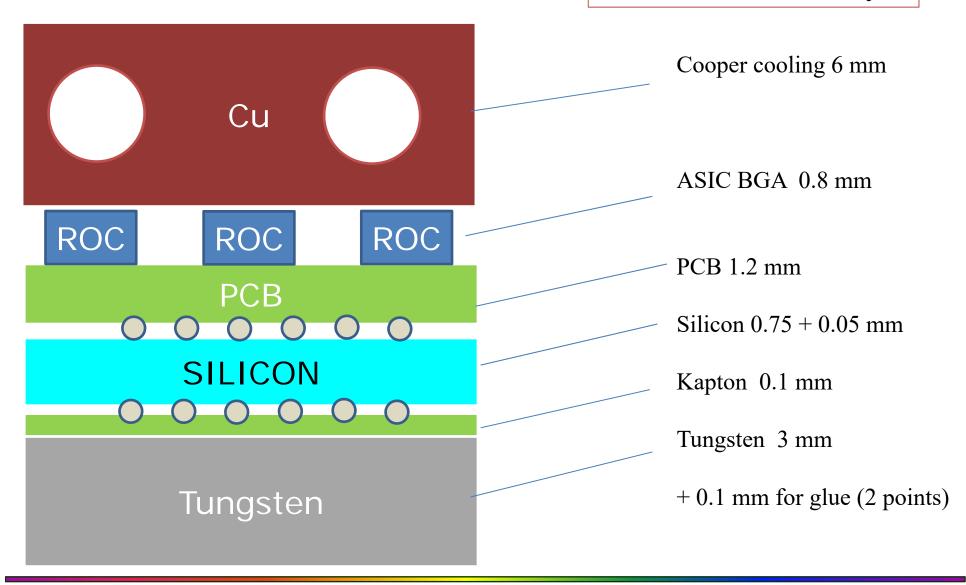






## **COOLING for continuous readout**

## TOTAL is 1.2 cm/Layer





## Korean industry and labs in France

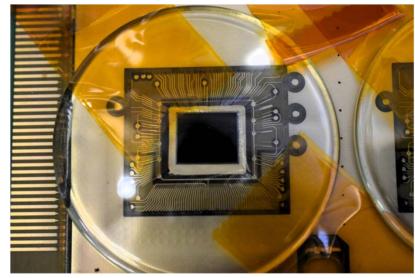




#### FEV-COB (Chip-On-Board)

- 2 FEV12-COB, SK2a with one 6" wafer  $\times$  500 $\mu$ m
- long standing work from LAL+Omega +
- 1.2mm, 9 layer PCB
- Good planarity (metrology made in LAL)
- No extra components on board
- 4 boards wirebonded at CERN
- 2 FEV12-BGA, SK2a with one 6" wafer × 500µm
- Gluing @ LPNHE with 100% controlled Wafers pro & post-gluing

Connections to SL-Board made by GradConn connectors





A gain in thickness .... mitigate the effect of 4-6 mm of cooper for active cooling



## **NEXT**

- Goes from 6 to 8" wafers and from 500 to 750µm thickness
- Use the rectangle of the edge of the wafer and estimate the effect
- 20 layers ECAL prototype in Test beam
- Take decision on COB or BGA
- Continue the collaboration with industry



What to do to go for such a detector

PANDORA ARBOR

Design (G4 and Reconstruction )

Prototypes, tests beam, G4 based design

We are here

- Industrial design
- Costing
- Engineering
- Organization at the stage of pre-construction

#### **Color code**

Well advanced **In progress** 

Not really started



#### **CONSTRUCTION**

Organisation, resp. sharing,

Risks mitigation, industrial constraints,

Final design, etc...



## Summary

- Silicon tungsten ECAL is making a lot of progress toward a scalable version
- Performances on s/n in test beam is perfect, as expected
- Active cooling for CEPC ... CMS-HGCAL as prototype
- No show-stopper, even the cost
- Going from labs to real detector will needs a lot of effort and people .... Open to collaboration

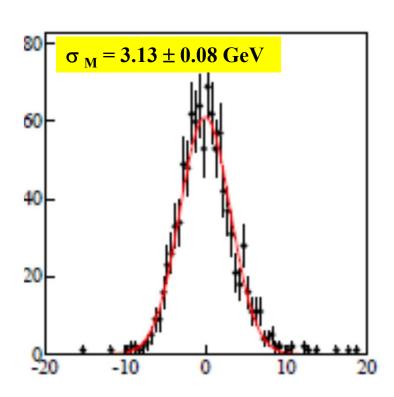


# BACKUP



## First study on PFA

# Visible energy resolution with PFA TESLA Report - 2001



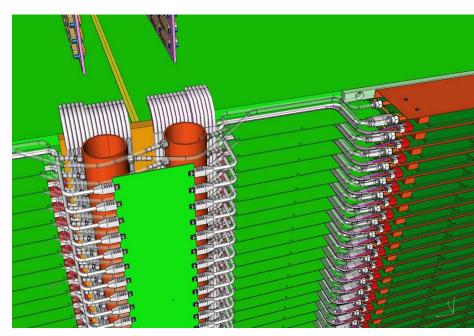
The resolution is about 3.1 GeV!!

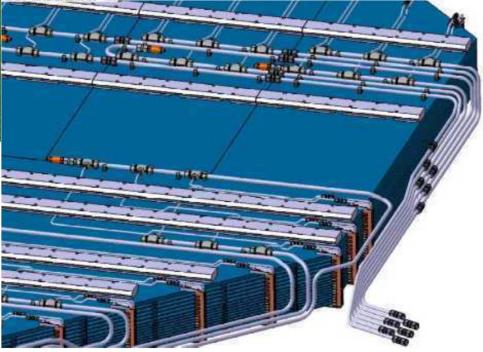
A factor 2 better than LHC experiments

J-C Brient, D.Orlando TESLA Report



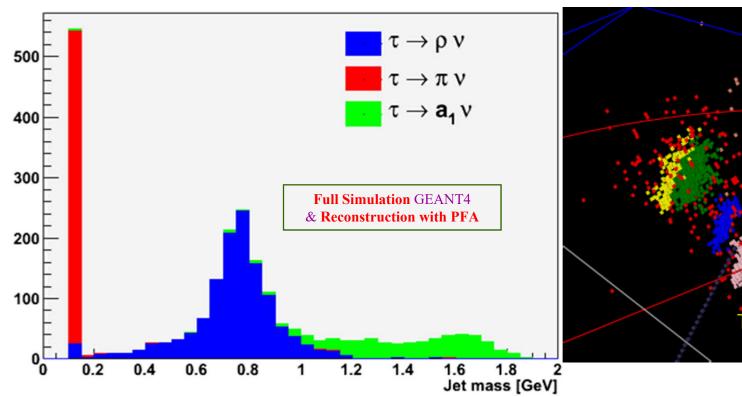
## **Enginering design of the cooling**

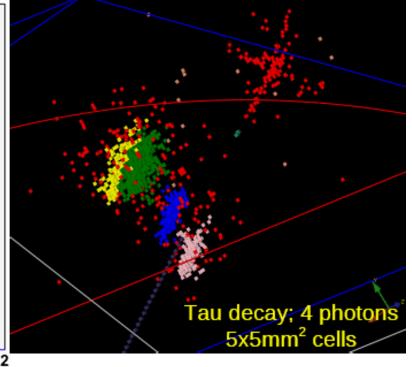




#### Invariant Mass from $\boldsymbol{\tau}$ decays

## Thanks you to granularity and segmentation!!





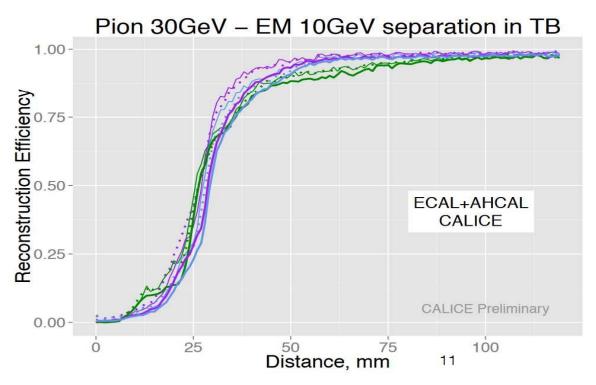
	Jet mass < 0.2	Jet mass in 0.2-1.1	Jet mass >1.1
$\tau \to \pi \nu$	90.2 %	1.7 %	8.1 %
$\tau \rightarrow \rho \nu$	1.7 %	87.3 %	7.4%
$\tau \rightarrow a_1 \nu$	0.6 %	7.4 %	92.0 %

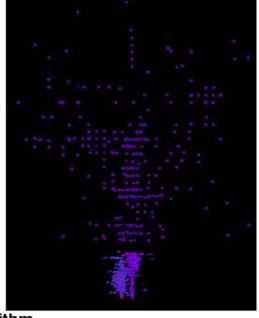


## Hadron-EM separation: 30+10 GeV $\pi^+$ -e+ (TB+MC), $\pi^+$ - $\gamma$ (MC)

Probability to reconstruct exactly one  $\gamma$  & one  $\pi$ <sup>+</sup> for Pandora or one  $\gamma$  for Garlic (which does not reconstruct hadrons), Arbor not used for AHCAL.

Good agreement between TB and MC.





#### **Algorithm**

- Garlic
- PandoraPandoraOLD

#### **MCTBparticle**

- MC:pi+e+
- · · MC:pi+phot
- ТВ:рі+е+



Data:  $\pi^+$ , e<sup>+</sup> CERN'07, ECAL+AHCAL MC:  $\pi^+$ , e<sup>+</sup>,  $\gamma$  TBCERN0807\_p0709

PFA: Pandora (v00-14 & v02-04) Garlic (v2.11), only ECAL





#### "LARGE" versus "SMALL"

